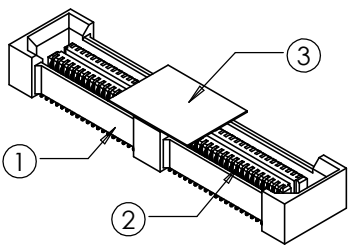
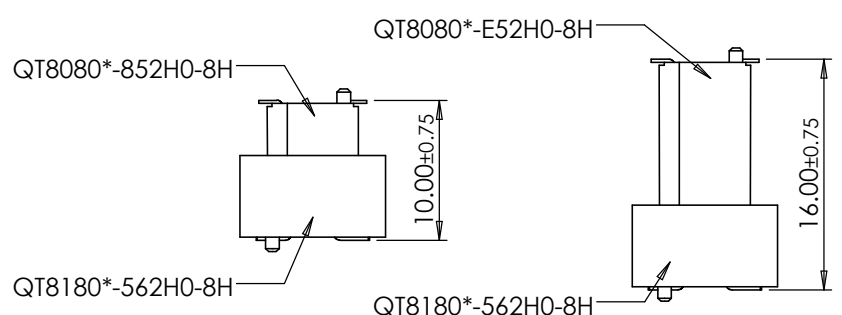
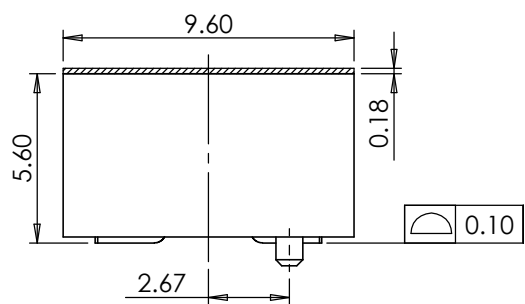


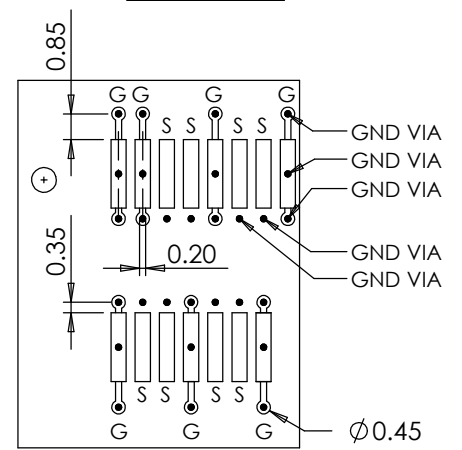
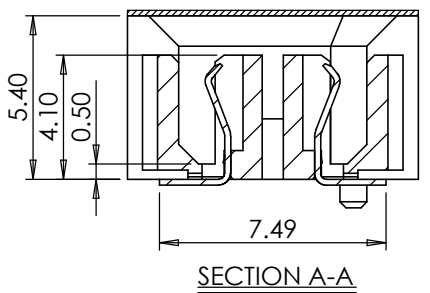
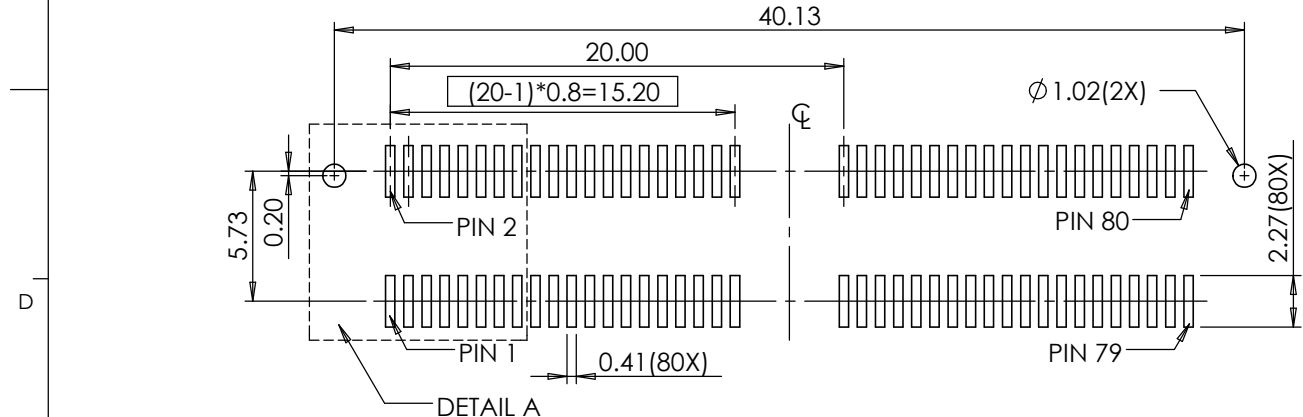
REV.	ECN NO.	APPD.
X1	20191217	Davy Bu



- 1.DIMENSIONS SHALL BE INTERPRETED PER ASME Y14,5M-2009.
- 2.ELECTRICAL CHARACTERISTICS:
 - 2.1:CONTACT CURRENT RATING:2.0 AMPERE D.C MAX,CONTINUOUSLY
 - 2.2:LOW LEVEL CONTACT RESISTANCE:
60 MILLIOHMS MAX.(INITIAL), Δ <20 MILLIOHMS FINAL.
 - 2.3:DIELECTRIC WITHSTANDING VOLTAGE:500V AC FOR 1 MINUTE.
 - 2.4:INSULATION RESISTANCE: 5000 MEGOHMS MIN.
- 3.MECHANICAL CHARACTERISTICS:
 - 3.1:MATING FORCE: 4kgf MAX..
 - 3.2:UN-MATING FORCE : 0.5kgf MIN..
 - 3.3:DURABILITY(MATING CYCLES):200 CYCLES.
- 4.ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE RANGE:-55°C TO +105°C.
- 5.PLEASE CONTACT FOXCONN SALES PRESENTATIVE TO VERIFY PRODUCT
DETAIL & AVAILABILITY.
- 6.THE PRODUCTS SHOULD MEET THE R.O.S.H. REQUIREMENT.



MATING VIEW



DETAIL A
SCALE 4:1

RECOMMEND PCB LAYOUT
GENERAL TOLERANCE ± 0.05

QT8180*-562H0-8H

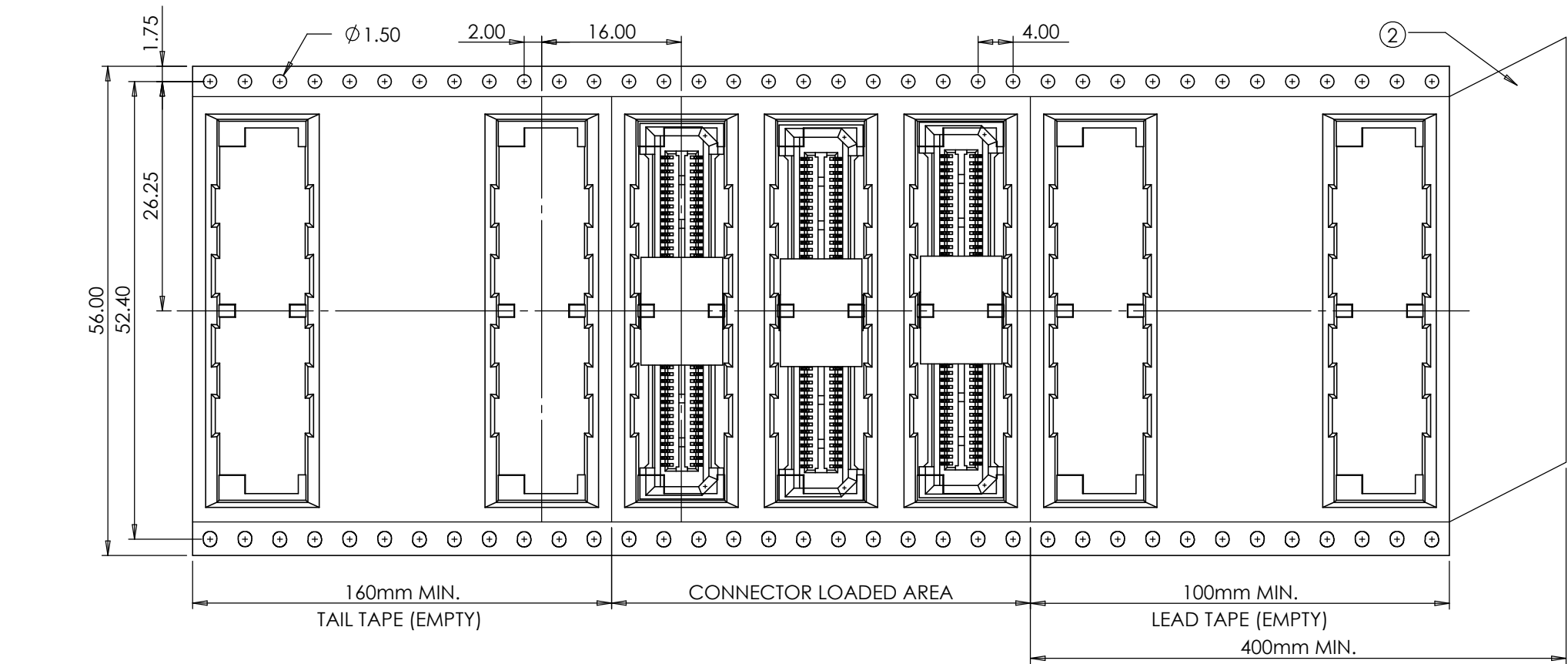
PITCH: 8=0.8mm
1=REC.
POS. NO.: 80=80POS.

H=HALOGEN FREE & LEAD FREE
PACKAGE CODE:
8=TAPE & REEL WITH PI-FILM
POST:
2=WITH POST
HEIGHT:56=5.60mm
CONTACT PLATING ARE:
1=1u" MIN. GOLD PLATING
Y=5u" MIN. GOLD PLATING
6=10u" MIN. GOLD PLATING
7=15u" MIN. GOLD PLATING
3=30u" MIN. GOLD PLATING

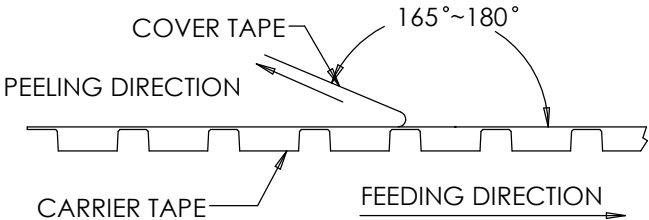
3	PI-FILM	1	POLYIMIDE	ADHESIVE		
2	CONTACT	80	COPPER ALLOY	GOLD PLATING ON CONTACT AREA. 80U" MIN. MATTE TIN PLATING ON SOLDER AREA. 50U" MIN. Ni UNDER PLATING.		
1	HOUSING	1	THERMOPLASTIC	UL 94V-0 BLACK		
ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT		REMARK
X. ± 0.50	X. ° ±	UNITS MM	NAME(INTENDED USE) BTB 0.8P 80POS. REC. CONN.	</		

SOLIDWORKS GENERATED DRAWING.DON'T CHANGE BY HAND.

REV.	ECN NO.	APPD.



- NOTES:
1. 10 POCKETS HOLE PITCH CUMULATIVE TOLERANCE $\pm 0.20\text{mm}$.
 2. COVER TAPE PEELING STRENGTH : 0.13 Kgf MAX. AT 300mm/min.



3. PACKAGING CAPACITY:

PCS/REEL	REEL/BOX	PCS/BOX
550	4	2200

3	REEL	POLYSTYRENT
2	COVER TAPE	POLYESTER
1	CARRIER TAPE	POLYSTYRENT
ITEM	DESCRIPTION	MATERIAL

X. ± 0.50	X. $^{\circ} \pm$	UNITS	MM	NAME(INTENDED USE)
.X ± 0.30	.X $^{\circ} \pm$	MAT'L		PACKAGE
.XX ± 0.20	.XX $^{\circ} \pm$			PART NO.(INTENDED USE)
.XXX ± 0.10	.XXX $^{\circ} \pm$	FINISH		QT8180*-562H0-8H
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				CHKD: J.K.Zhu
				DR: X.J Lin 12/14'19

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CLASS: ☐ CONFIDENTIAL ☐ SECRET ☒ GENERAL			
TITLE: CUSTOMER DRAWING			
DWG NO.: 323-0000-1961			
	SCALE	SHEET	REV.
	N/A	2/2	X1